





## My Take on ASP-DAC on its 20<sup>th</sup> Anniversary

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## **Congratulations to ASP-DAC!**





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#### **Disclaimer**

- I am truly honored and humbled to be asked to give this talk, for the 20<sup>th</sup> anniversary celebration
- There are many, many key contributors of ASP-DAC who are more qualified than me to give this talk, in particular, on the history of ASP-DAC, etc. (I need to grow more gray hairs for that ☺)
- I will share my personal experience and perspective

#### So, where was I in 1995?

- The first ASP-DAC was held 08.29-9.1.1995 in Makuhari
- At that time, I was a graduate student in Physical Sciences
- Just took an introductory CS class
- Know nothing about VLSI or CAD
- ◆ So, I was really a new born baby in EDA ☺



Luckily, I met Prof. Jason Cong who introduced me into the new world of EDA





### **My ASP-DAC History**

- My first ASP-DAC paper in 1999 (Hong Kong)
- My second ASP-DAC paper in 2001 (Japan)
- **♦** -----
- My first physical attendance at ASP-DAC was actually 2005
   − exactly 10 years ago in Shanghai ☺
  - G. Xu, L. Huang, D. Z. Pan and M. D.-F. Wong, "Redundant-Via Enhanced Maze Routing for Yield Improvement"
  - > 10-year Retrospective Most Influential Paper Award Candidate
- Regularly submit papers to ASP-DAC
  - 30 papers at ASP-DAC (including several invited papers)
- Best Paper Award twice (2010 and 2012)
- Best Paper Award Nomination in 2006, 2008, 2013
- ASP-DAC Frequently Cited Author Award

#### My first ASP-DAC paper, in 1999

## Interconnect Delay Estimation Models for Synthesis and Design Planning

Jason Cong and David Z. Pan

UCLA Computer Science Department Los Angeles, CA 90095

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### **Interconnect Layout Optimization**

- ◆ E.g., UCLA **TRIO** (Tree, Repeater, Interconnect Optimization) Package
  - Interconnect topology optimization
  - Optimal buffer insertion
  - Wiresizing optimization
  - Global interconnect sizing and spacing
  - Simultaneous driver, buffer & interconnect sizing
  - Simultaneous topology generation with buffer insertion and wiresizing
- Delay can be improved many times

- Develop a set of delay estimation models, under different optimizations such as wire sizing, driver sizing, buffer insertion/sizing, etc.
  - Closed-form formula or simple characteristic equations
  - Constant running time in practice
  - High accuracy (about 90% on average)
  - Great for interconnect planning

#### Impacts:

- Citation: 68 (based on Google Scholar)
- Widely adopted by industry (IBM, Freescale, Intel, etc.)
- Jason Cong's SRC Technical Excellence Award in 2000, for "Interconnect Estimation, Planning and Synthesis for Deep Sub-micron Designs"

## My second ASP-DAC paper, in 2001

## Improved Crosstalk Modeling for Noise Constrained Interconnect Optimization

Jason Cong, Zhigang (David) Pan, and P.V. Srinivas\*

Computer Science Department
University of California, Los Angeles
\* Magma Design Automation Inc.



Sponsored by SRC

- Develop a closed-form crosstalk noise model, which has high fidelity cf. detailed spice simulations
- Unified previous crosstalk noise models
- Great to guide crosstalk optimizations during physical synthesis (buffer insertion, driver sizing, spacing, ...)

#### Impacts:

- > Citation: 146
- US Patent issued
- Used by Magma (acquired by Synopsys)

#### My first physical presence at ASP-DAC, Shanghai, 2005

## Redundant Via Enhanced Maze Routing for Yield Improvement

Gang Xu

CS Department University of Texas at Austin xugang@cs.utexas.edu Li-Da Huang

Texas Instruments lida@ti.com David Z. Pan

ECE Department University of Texas at Austin dpan@ece.utexas.edu Martin D.F. Wong

ECE Department University of Illinois at Urbana-Champaign mdfwong@uiuc.edu

- The first paper on redundant via aware routing
- Proposed on-track, off-track redundant vias
- Constrained optimization with Lagrangian Relaxation
- Impacts:
  - Citation: 91
  - 10-year Retrospective Most Influential Paper Award Candidate
  - The first paper on redundant via aware routing
  - All major fabs strongly recommend redundant vias
  - All modern EDA commercial routers have redundant via insertion awareness





## MeshWorks: An Efficient Framework for Planning, Synthesis & Optimization of Clock Mesh Networks

Anand Rajaram§\* and David Z. Pan§

§ ECE Department, University of Texas at Austin.

\* DDSP, Texas Instruments, Dallas.

- We proposed a systematic methodology for clock mesh planning, synthesis, and optimization
- Impacts:
  - Citation: 42
  - ASP-DAC'08 Best Paper Candidate
  - The first paper on fully automatic clock mesh synthesis
  - Clock mesh design was mostly done manually before
  - Now it is available in EDA tools as high-performance ASIC designs may need some mesh-like structures to deal with PVT variations



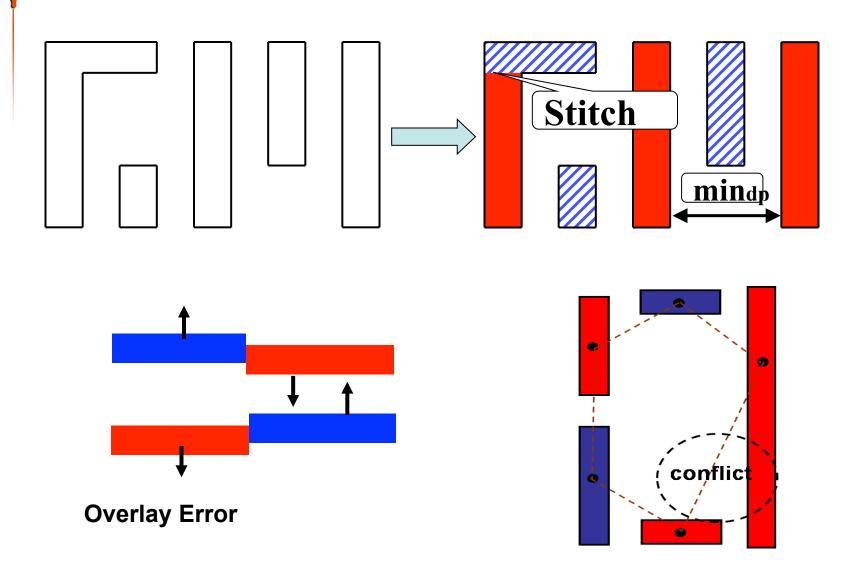


## A New Graph-Theoretic, Multi-Objective Layout Decomposition Framework for Double Patterning Lithography

Jae-Seok Yang, Katrina Lu, Minsik Cho, Kun Yuan, and David Z. Pan

**ECE Department, University of Texas at Austin** 

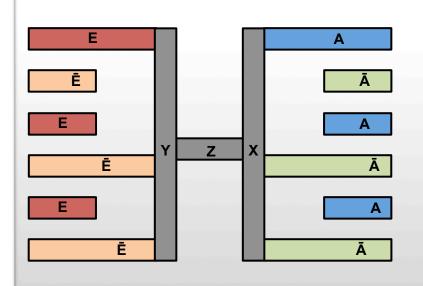
## **What is Double Patterning?**

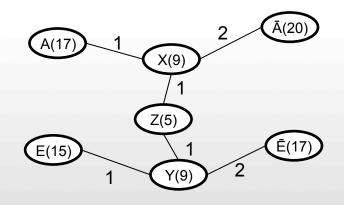


#### A Graph-Partitioning Based, Multi-Objective Decomposer

#### **Decomposition Graph Construction**

#### [Yang+, ASPDAC10]





Constraint:  $(A, \bar{A})$  and  $(E, \bar{E})$  are repulsive pairs.

Theorem: Stitch minimization problem is equivalent to the min-cut partitioning of the decomposition graph

Extensions of the framework: to incorporate other constraints and costs into graph partitioning, e.g., balanced density, overlay compensation, and so on

- First holistic framework to consider overlay compensation, stitch minimization, and balanced density together
- Easily adjust weights/multi-objective; very fast
- Impacts:
  - Citation: 51
  - ASP-DAC 2010 Best Paper Award
  - IBM Research 2010 Pat Goldberg Memorial Best Paper Award in CS/EE/Math (among all papers in very broad areas under CS, EE, and mathematical sciences co-authored by IBM's 4000+ researchers in 2010)
  - Industry usage of double/triple patterning (layout decomposition is a key step for both mask/PD)

#### **Back in 2003**



"Daddy, don't worry. I can show you some **bright** idea!"



"Double patterning!!!"



#### **ASPDAC 2012, Sydney**



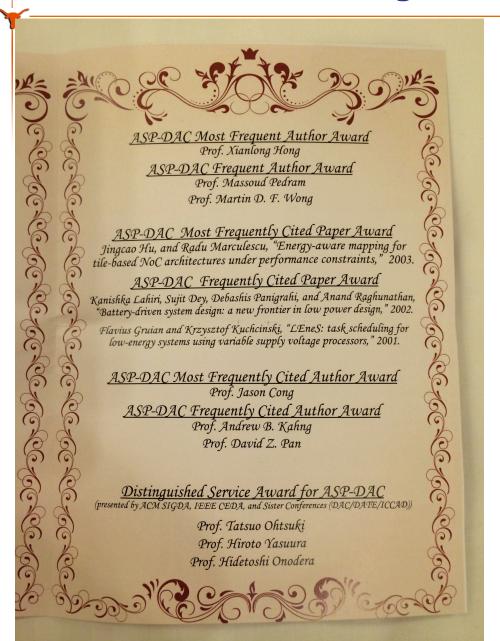
# EPIC: Efficient Prediction of IC Manufacturing Hotspots using a Unified Meta-Classification Method

Duo Ding, Bei Yu, Joydeep Ghosh and David Z. Pan Dept. of Electrical and Computer Engineering The Univ. of Texas at Austin

http://www.cerc.utexas.edu/utda

- Proposed a novel meta-classification method to unify machine learning and pattern matching methods together
- Impacts:
  - ASP-DAC 2012 Best Paper Award
  - ASP-DAC 2011 paper: "High performance lithographic hotspot detection using hierarchically refined machine learning" (citation: 30)
  - Helped spark the ICCAD 2012 CAD Contest, organized by Mentor Graphics, on "Lithography Hotspot Detection" (many teams participated)
  - Very well attended ASPDAC'15 Special Session on "Machine Learning in EDA" yesterday

## **ASP-DAC** is Truly International



## ASP-DAC Top Authors (based on DBLP, up to 2014)

Xianlong Hong (56)

Massoud Pedram (41)

Martin D. F. Wong (38)

Yici Cai (36)

Chung-Kuan Cheng (34)

Jason Cong (33)

Hidetoshi Onodera (29)

Sheldon X.-D. Tan (28)

David Z. Pan (27)

Yuan Xie (26)

Andrew B. Kahng (25)

Sung Kyu Lim (23)

Hai Zhou (22)

Kwang-Ting Cheng (21)

Masanori Hashimoto (21)

Jing-Yang Jou (20)

Sachin S. Sapatnekar (20)

Kenichi Okada (20)

Kaushik Roy (20)

Nozomu Togawa (19)

Tsutomu Sasao (19)

Lei He (19)

Rolf Drechsler (19)

Yao-Wen Chang (19)

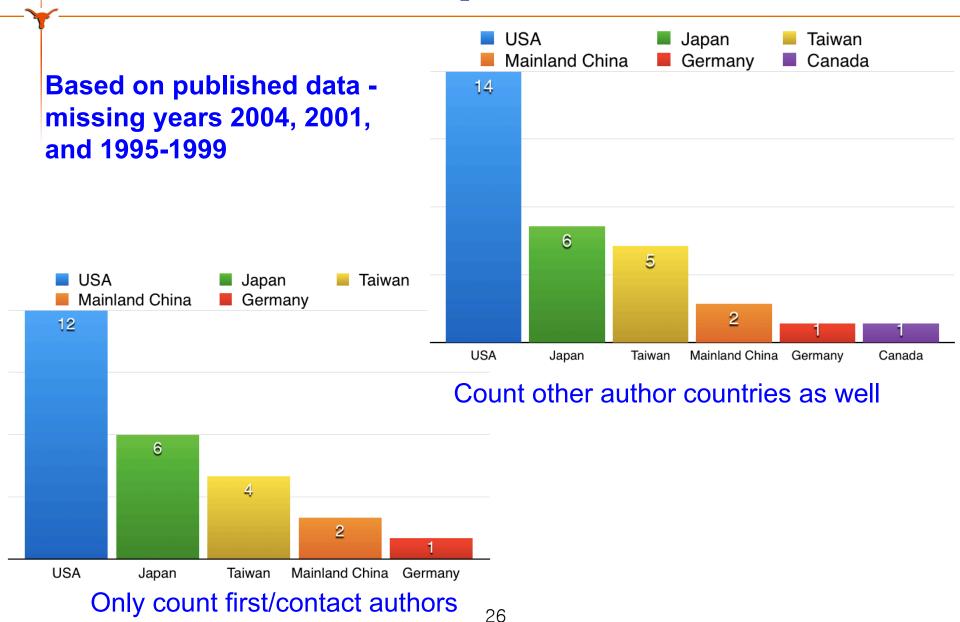
#### **How to Win an ASP-DAC BPA?**

I hope I have a secret sauce



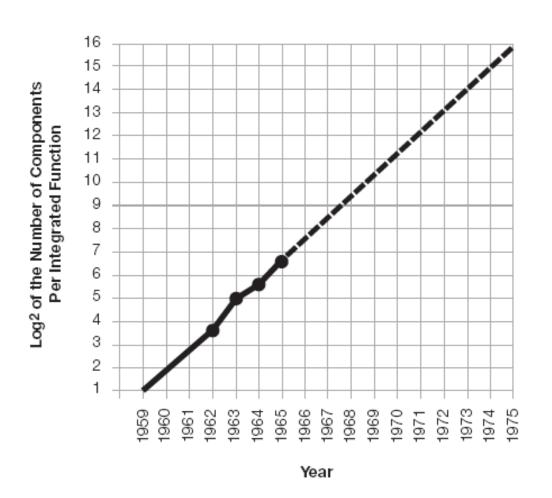
- Seriously, just submit your best work to ASP-DAC
- Then don't worry about it
- Right topic + elegant algorithm + a lot of luck!

## **ASP-DAC Best Paper Statistics**



## **Moore's Law 50th Anniversary!**

Moore's original paper in 1965



[Moore, 1965]

#### **Moore's Law Amendment**

#### NO EXPONENTIAL IS FOREVER...

**BUT** 

**WE CAN DELEY "FOREVER"** 

#### **Future "EDA" Research**

- More Moore: continue pushing the envelope, 14nm, 11nm, 7nm
  - Multiple patterning and emerging lithography
  - Computational scaling (CAD tools still very sub-optimal)
- More than Moore: New CAD issues
  - Vertically 3D IC integration
  - New device/material: FINFET, III-V, graphene, ...
  - New domains: Bio, Photonic, ...
  - New applications: energy, big data, security, automotive, ...
- "EDA" Extreme Difficulty Automation
  - You can do anything if you can handle "EDA"

